ALPHA & OMEGA SEMICONDUCTOR

AOTF260L

60V N-Channel MOSFET

General Description

The AOTF260L uses Trench MOSFET technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$, Ciss and Coss. This device is ideal for boost converters and synchronous rectifiers for consumer, telecom, industrial power supplies and LED backlighting.

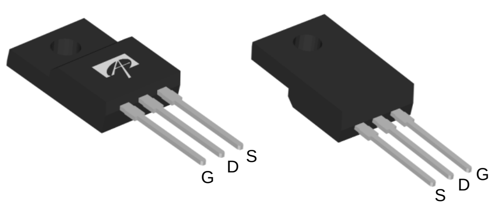
Product Summary

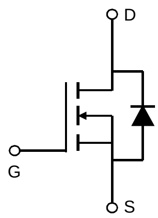
V_{DS}	60V
I_D (at V_{GS}=10V)	92A
$R_{DS(ON)}$ (at V_{GS}=10V)	< 2.6mΩ
$R_{DS(ON)}$ (at V_{GS}=6V)	< 3.0mΩ

100% UIS Tested
100% R_g Tested

Green Product

TO220F





Absolute Maximum Ratings T_A=25°C unless otherwise noted				
Parameter		**Symbol**	**Maximum**	**Units**
Drain-Source Voltage		V_{DS}	60	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current [G]	T_C=25°C	I_D	92	A
	T_C=100°C		66.5	
Pulsed Drain Current [C]		I_{DM}	368	
Continuous Drain Current	T_A=25°C	I_{DSM}	19	A
	T_A=70°C		15	
Avalanche Current [C]		I_{AS}	128	A
Avalanche energy L=0.1mH [C]		E_{AS}	819	mJ
Power Dissipation [B]	T_C=25°C	P_D	46.5	W
	T_C=100°C		23.5	
Power Dissipation [A]	T_A=25°C	P_{DSM}	1.9	W
	T_A=70°C		1.2	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 175	°C

Thermal Characteristics					
Parameter		**Symbol**	**Typ**	**Max**	**Units**
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	12	15	°C/W
Maximum Junction-to-Ambient [A D]	Steady-State		54	65	°C/W
Maximum Junction-to-Case	Steady-State	$R_{\theta JC}$	2.6	3.2	°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions		Min	Typ	Max	Units
STATIC PARAMETERS							
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250µA, V_{GS}=0V		60			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=60V, V_{GS}=0V				1	µA
			T_J=55°C			5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±20V				±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250µA		2.2	2.7	3.2	V
$I_{D(ON)}$	On state drain current	V_{GS}=10V, V_{DS}=5V		368			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=20A			2.1	2.6	mΩ
			T_J=125°C		3.5	4.3	
		V_{GS}=6V, I_D=20A			2.3	3.0	
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=20A			68		S
V_{SD}	Diode Forward Voltage	I_S=1A, V_{GS}=0V			0.65	1	V
I_S	Maximum Body-Diode Continuous Current					55	A
DYNAMIC PARAMETERS							
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=30V, f=1MHz			11800		pF
C_{oss}	Output Capacitance				1360		pF
C_{rss}	Reverse Transfer Capacitance				40		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz		0.5	1	1.5	Ω
SWITCHING PARAMETERS							
Q_g(10V)	Total Gate Charge	V_{GS}=10V, V_{DS}=30V, I_D=20A			150	210	nC
Q_{gs}	Gate Source Charge				40		nC
Q_{gd}	Gate Drain Charge				15		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=30V, R_L=1.5Ω, R_{GEN}=3Ω			30		ns
t_r	Turn-On Rise Time				27		ns
$t_{D(off)}$	Turn-Off DelayTime				74		ns
t_f	Turn-Off Fall Time				12		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=20A, dI/dt=500A/µs			32		ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=20A, dI/dt=500A/µs			200		nC

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175°C may be used if the PCB allows it.
B. The power dissipation P_D is based on $T_{J(MAX)}$=175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
C. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=175°C. Ratings are based on low frequency and duty cycles to keep initial T_J=25°C.
D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.
E. The static characteristics in Figures 1 to 6 are obtained using <300µs pulses, duty cycle 0.5% max.
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=175°C. The SOA curve provides a single pulse rating.
G. The maximum current rating is package limited.
H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

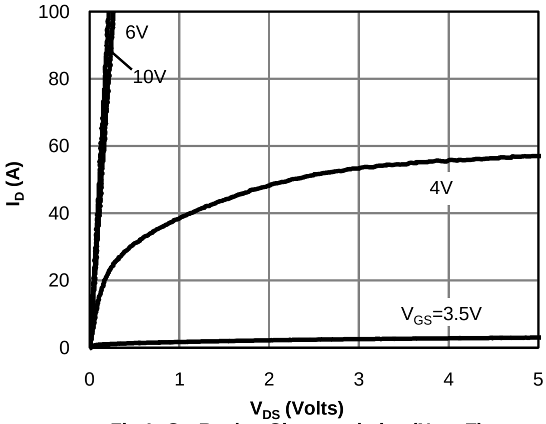


Fig 1: On-Region Characteristics (Note E)

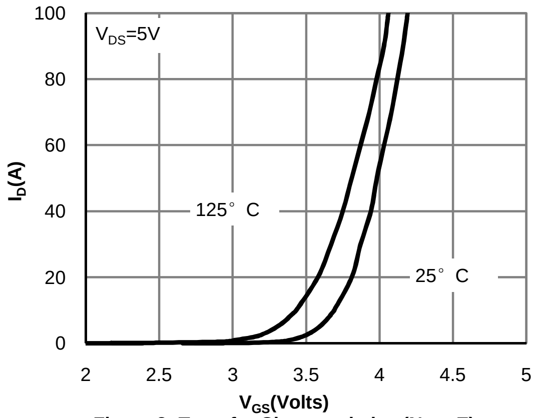


Figure 2: Transfer Characteristics (Note E)

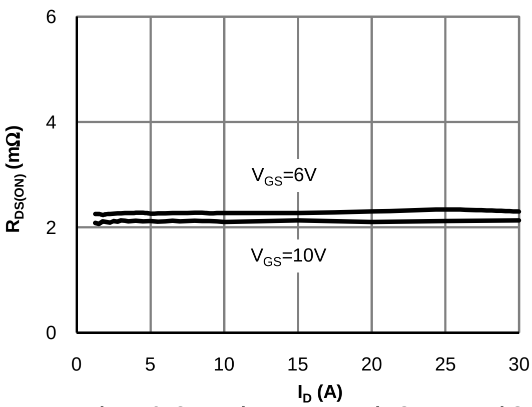


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

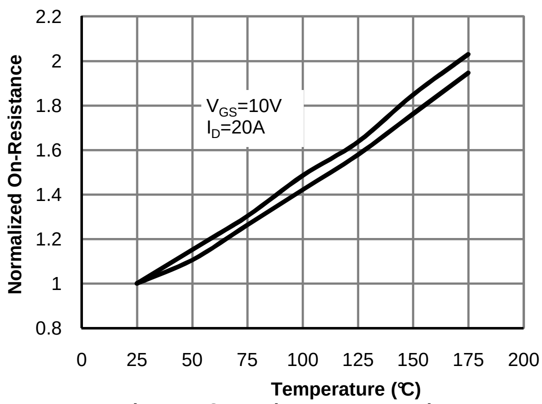


Figure 4: On-Resistance vs. Junction Temperature (Note E)

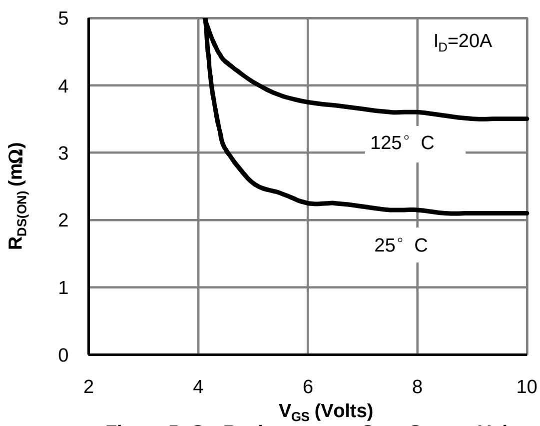


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

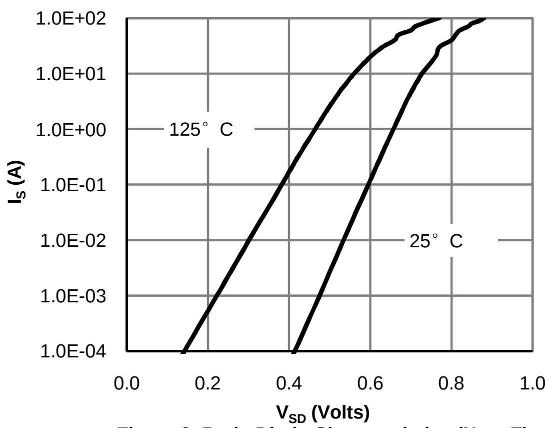


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

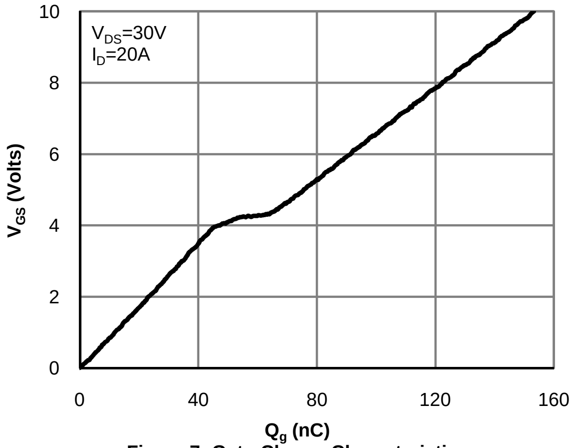


Figure 7: Gate-Charge Characteristics

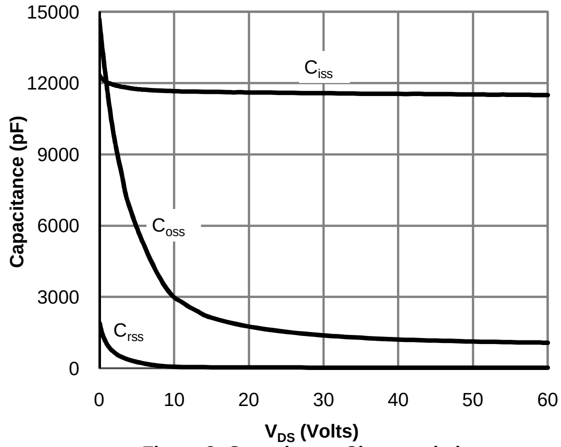


Figure 8: Capacitance Characteristics

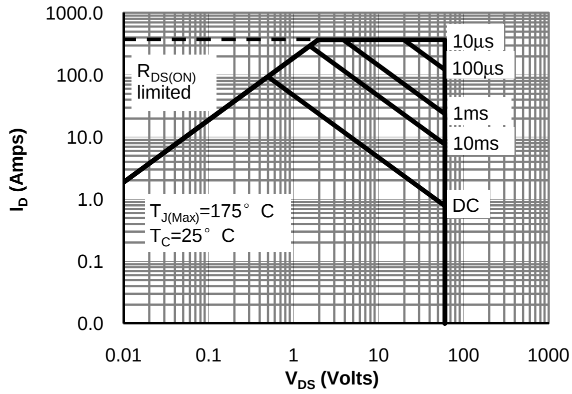


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

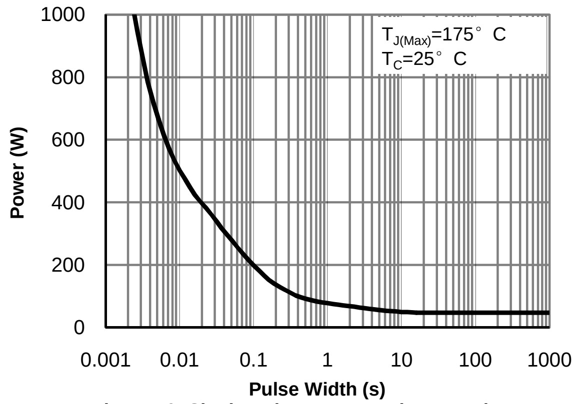


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

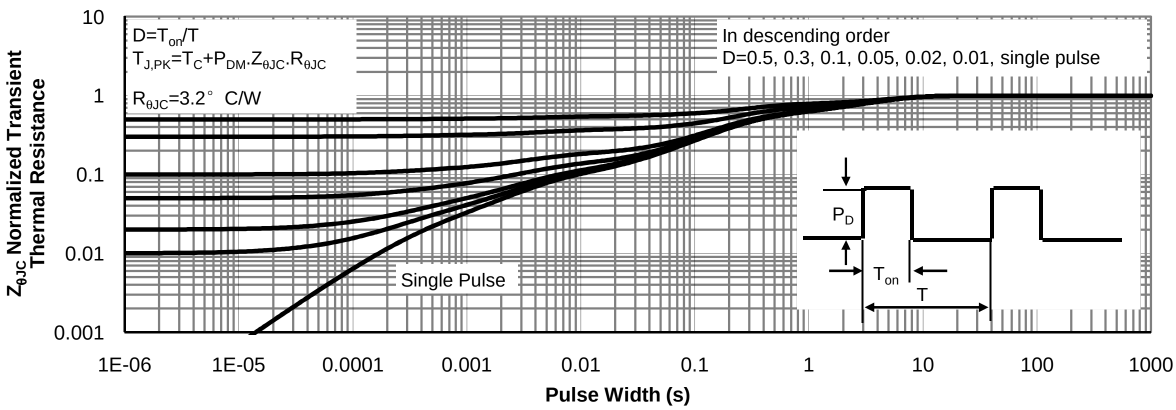


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

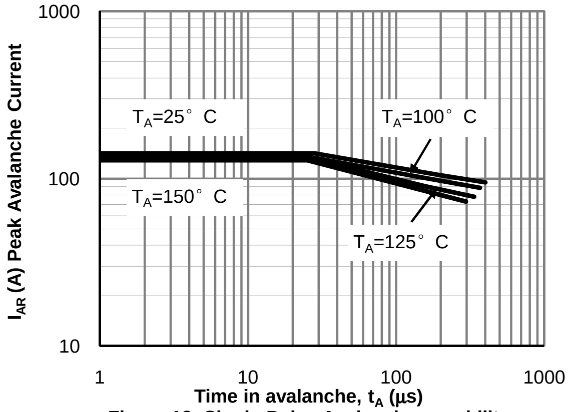


Figure 12: Single Pulse Avalanche capability (Note C)

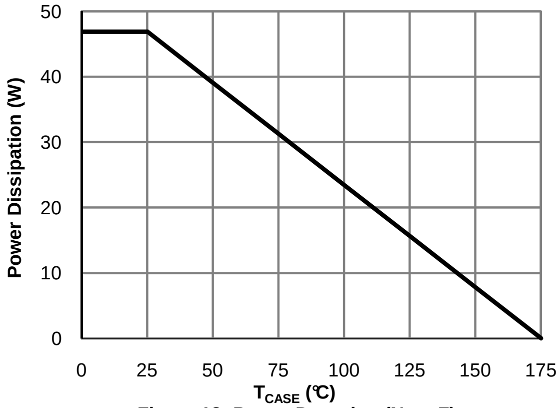


Figure 13: Power De-rating (Note F)

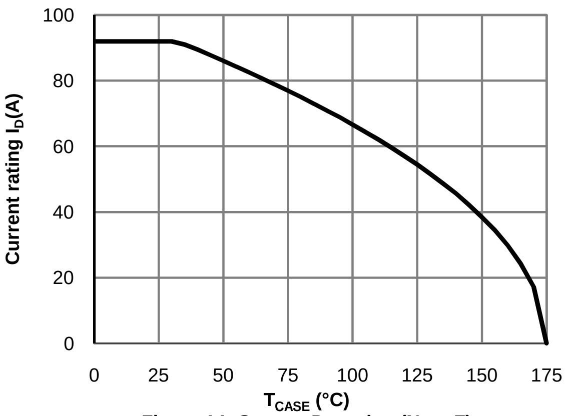


Figure 14: Current De-rating (Note F)

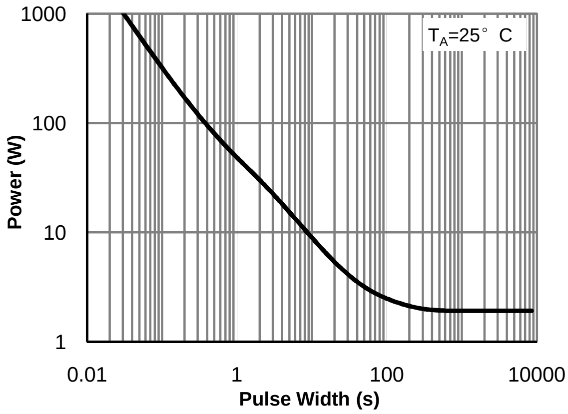


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

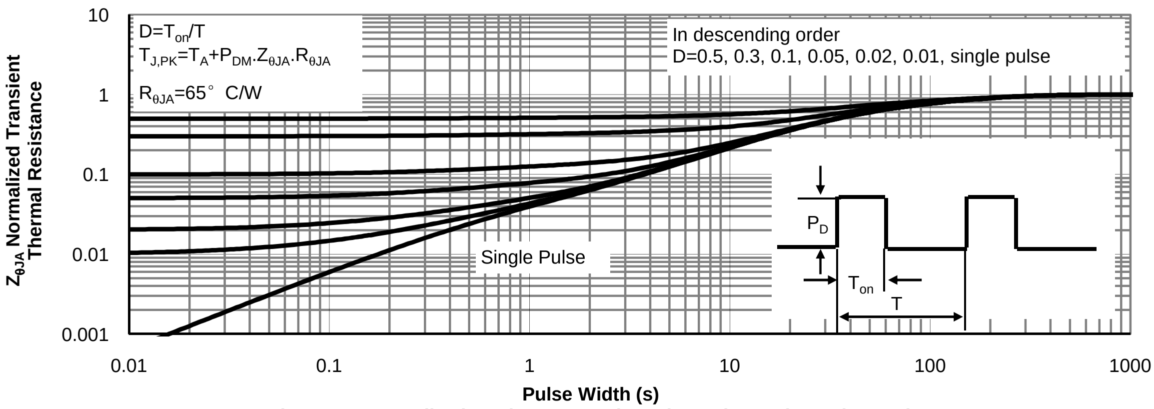
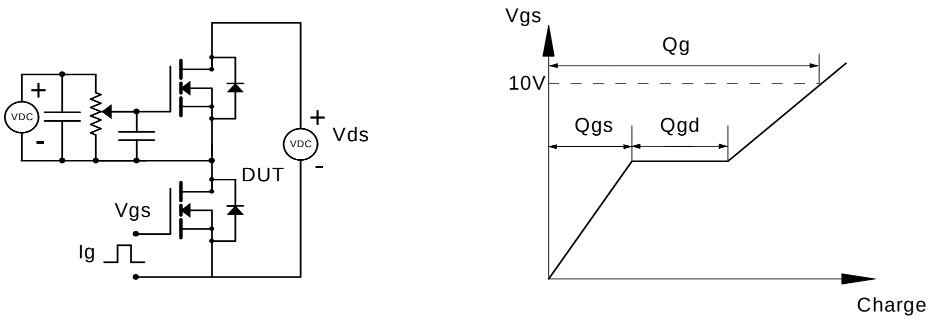
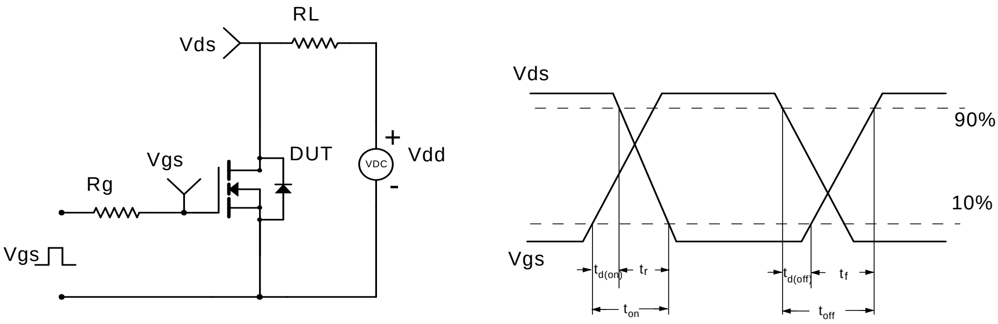


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)

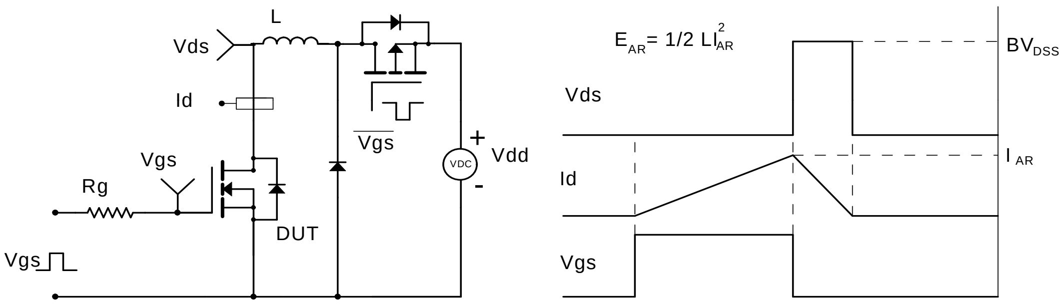
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms